



Product/Process Change Notice - PCN 25_0131 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	Bond Wire Conversion from Gold to Copper for ADSP-2158x Processors
Publication Date:	14-May-2025
Effectivity Date:	16-Aug-2025 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	Initial Release

Description Of Change:

Change of bond wire material from Gold (Au) to Copper (Cu) for select BGA products. Bond wire thickness remains 0.8 mil with no change.

Reason For Change:

The conversion to Cu wire aligns with industry trend and ADI current and future corporate directives.

Impact of the change (positive or negative) on fit, form, function & reliability:

This change has no impact on fit, form, function or reliability.

Product Identification: *(this section will describe how to identify the changed material)*

Analog Device maintains full traceability by device marking/labeling/shipment documents. Change will be differentiated by date code.

Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Delta Qualification Matrix

ADI_PCN_25_0131_Rev_-_Delta-Qualification-Matrix-ZVEI-5_1_8.xlsxm

Attachment 2: Type: Qualification Results Summary

ADI_PCN_25_0131_Rev_-_ADSP-SC58xADSP-2158x Cu Wire Qualification.pdf

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (26)

ADSP-21583 / ADSP-21583BBCZ-4A	ADSP-21583 / ADSP-21583KBCZ-4A	ADSP-21584 / ADSP-21584BBCZ-4A	ADSP-21584 / ADSP-21584CBCZ-4A	ADSP-21584 / ADSP-21584KBCZ-4A
ADSP-21584 / ADSP-21584KBCZ-5A	ADSP-21584-D / ADSP-21584KBCZ5AD3	ADSP-21584W-10 / ADW95159Z-10	ADSP-21584W-10 / ADW95159Z-10RL	ADSP-21584W-12 / AD21584WCBCZ4A12
ADSP-21584W-12 / ADW95159Z-12RL	ADSP-21584W-13 / ADW95167Z-13	ADSP-21584W-13 / ADW95167Z-13RL	ADSP-SC582 / ADSP-SC582BBCZ-4A	ADSP-SC582 / ADSP-SC582KBCZ-4A
ADSP-SC583 / ADSP-SC583KBCZ-4A	ADSP-SC584 / ADSP-SC584BBCZ-4A	ADSP-SC584 / ADSP-SC584BBCZ-5A	ADSP-SC584 / ADSP-SC584CBCZ-4A	ADSP-SC584 / ADSP-SC584CBCZ-5A
ADSP-SC584 / ADSP-SC584KBCZ-4A	ADSP-SC584 / ADSP-SC584KBCZ-5A	ADSP-SC584W-10 / ADW95148Z-10RL	ADSP-SC584W-12 / ADSC584WCBCZ4A12	ADSP-SC584W-12 / ADW95174Z-12RL
ADSP-SC584W-13 / ADW95166Z-13ARL				

Appendix B - Revision History:

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	14-May-2025	16-Aug-2025	Initial Release